

**NDS Compliant**

## TECHNICAL CHARACTERISTICS

### 1. General Characteristics

Dimension: 16.15L x 16.90W x 4.60H mm  
 Standoff H= 2.00 mm  
 Weight: Approx. 0.87 g  
 Contact principle: Friction technology  
 Operating position: Shaft up / Down / Horizontal  
 Mounting System: SMT Type (without post)  
 Durability: 5,000 cycles min.

### 2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0  
 RoHS Directive 2011/65/EU Compliant

### 3. Electrical Characteristics

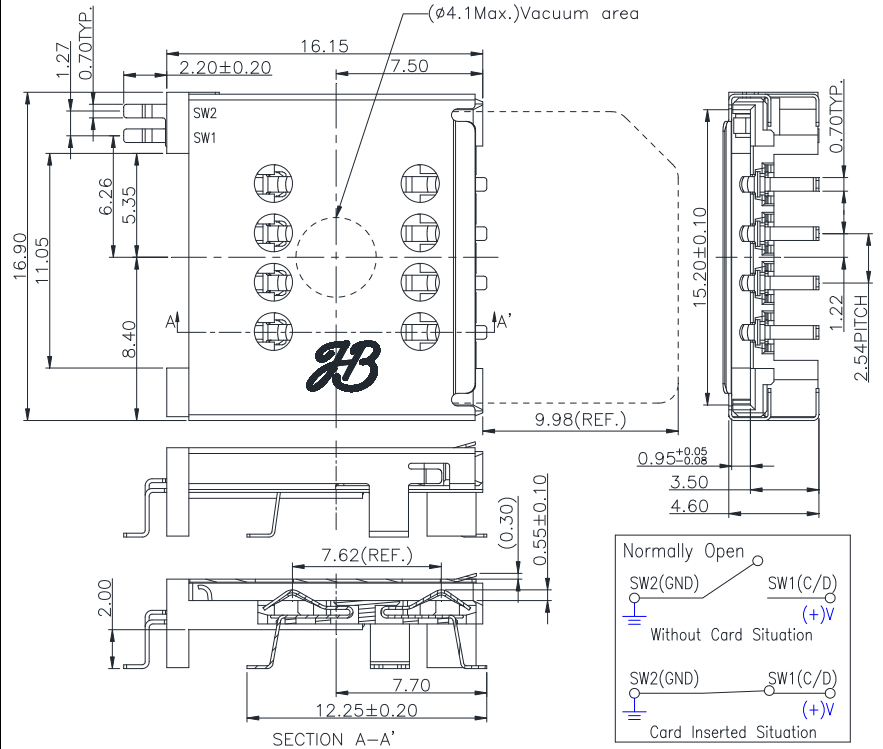
Number of contacts: 8 pins  
 Contact resistance: 50 mΩ typical, 100 mΩ max.  
 Insulation resistance: >1000 MΩ / 500 VDC  
 Switch type: Blade  
 Operation: Normally Open

### 4. Solderability

Wave: Not applicable  
 IR reflow: 260°C, 10 sec. Max.  
 Manual soldering: 360°C, 3 sec. Max.

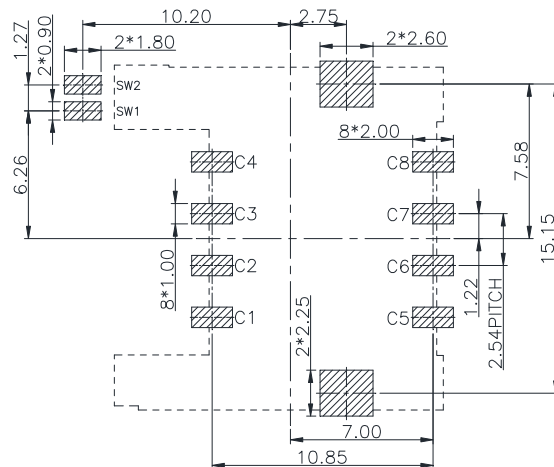
### 5. Environmental Characteristics

Operating temperature: - 40°C ~ + 90°C  
 Operating humidity: 10 % ~ 95 % RH  
 Storage temperature: - 40°C ~ + 90°C  
 Storage humidity: 10 % ~ 95 % RH



※Metal cover can't be pressed. Must keep 0.1 mm min. gap above cover.

Unit: mm; Tolerances: ±0.15 mm  
Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm  
Reference dimension for PCB layout

**HB SIM Card Connector**

**Model No.: ICC-323**

**Revision: 1.1**

**Date: MAY 09, 2018**

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.